high heat resistance, but still have been required to have higher heat resistance. Specifically, highly thermally conductive silicone sheets become hard at high temperature due to an increase in the amount of a filler filled or the use of a highly thermally conductive filler, and thus need to be improved.

Moreover, in the semiconductor field, the contamination by metal impurities has been a problem, and thus there has been a demand for heat-dissipating members that do not contain a heat resistance improver or a pigment made of a metal oxide or a metal complex.

[0005] To solve the above conventional problems, embodiments of the present invention provides a heat-resistant thermally conductive composition and a heat-resistant thermally conductive sheet that use a heat resistance improver containing no metal atom and that are less likely to become hard at high temperature.

Means for Solving Problem

[0006] ~~A heat-resistant thermally conductive composition of the present invention contains a matrix resin and thermally conductive particles. The heat-resistant thermally conductive composition contains a benzimidazolone compound as a heat resistance improver.~~

According to a first aspect of the present invention, there is provided a heat-resistant thermally conductive composition including: a matrix resin; and thermally conductive particles, wherein the heat-resistant thermally conductive composition contains a benzimidazolone compound as a heat resistance improver, and considering an amount of the matrix resin to be 100 parts by mass, the thermally conductive particles are added in an amount of 100 to 4000 parts by mass.

[0007] ~~A heat-resistant thermally conductive sheet of the present invention includes the heat-resistant thermally conductive composition in the form of a sheet.~~

According to a second aspect of the present invention, there is provided a heat-resistant thermally conductive sheet comprising the above heat-resistant thermally conductive composition in the form of a sheet.

Effects of the Invention

[0008] In embodiments of the present invention, the heat-resistant thermally conductive composition contains a matrix resin and thermally conductive particles, and contains a benzimidazolone compound as a heat resistance improver. Thus, embodiments of the present invention can provide the heat-resistant thermally conductive composition and the heat-resistant thermally conductive sheet that are less likely to become hard at high temperature. The benzimidazolone compound is usually known to be added as a pigment, but exhibits unpredictable effects of improving heat resistance. Moreover, the heat-resistant thermally conductive composition and the heat-resistant thermally conductive sheet use the heat resistance improver containing no metal atom and are less likely to become hard at high temperature. Thus, they are largely advantageous